L Number	Hits	Search Text	DB	Time stamp
1	0	(micrelectronic adj assembly) and juxtaposing and	USPAT	2004/05/07 16:06
		(microelectronic adj elements)		
2	65	(microelectronic adj assembly) and juxtaposing and	USPAT	2004/05/07 16:06
		(microelectronic adj elements)		
3	4	(microelectronic adj assembly) and juxtaposing and	USPAT	2004/05/07 16:13
		(microelectronic adj elements) and (major adj face)		
4	1	("5659952").PN.	USPAT	2004/05/07 16:13
5	1	(("5659952").PN.) and (microelectronic or assembly or	USPAT	2004/05/07 16:18
		element or elements or plurality or portion or separated or		
		dicing or wafer or substrate or dielectric or extending or		
		major or face or removing or along or exposing or protecitive		
		or adhesive or juxtaposing or juxtapose or region or unit or		
		individual)		
6	1	("5706174").PN.	USPAT	2004/05/07 16:17
7	1	(("5706174").PN.) and (microelectronic or assembly or	USPAT	2004/05/07 16:19
		element or elements or plurality or portion or separated or		
		dicing or wafer or substrate or dielectric or extending or		
1		major or face or removing or along or exposing or protecitive		
İ		or adhesive or juxtaposing or juxtapose or region or unit or		
		individual)	LICDAT	0004/05/07 17 10
8]	("6169328").PN.	USPAT	2004/05/07 16:19
9	1	(("6169328").PN.) and (microelectronic or assembly or	USPAT	2004/05/07 16:22
		element or elements or plurality or portion or separated or		
		dicing or wafer or substrate or dielectric or extending or		
		major or face or removing or along or exposing or protecitive		
		or adhesive or juxtaposing or juxtapose or region or unit or		
10		individual)	USPAT	2004/05/07 16:22
10 11	1	("5518964").PN.	USPAT	2004/05/07 16:22
11	•	(("5518964").PN.) and (microelectronic or assembly or element or elements or plurality or portion or separated or	USPAT	2004/03/07 10:36
		dicing or wafer or substrate or dielectric or extending or		
		major or face or removing or along or exposing or protecitive		
		or adhesive or juxtaposing or juxtapose or region or unit or		
		individual)		
12	1	("5148266").PN.	USPAT	2004/05/07 16:32
13	1	(("5148266").PN.) and (microelectronic or assembly or	USPAT	2004/05/07 16:34
'	•	element or elements or plurality or portion or separated or	u3.7(1	200 1/ 03/ 07 10:31
		dicing or wafer or substrate or dielectric or extending or		
		major or face or removing or along or exposing or protecitive		
		or adhesive or juxtaposing or juxtapose or region or unit or		
		individual)		
14	1	("5148265").PN.	USPAT	2004/05/07 16:34
15	1	(("5148265").PN.) and (microelectronic or assembly or	USPAT	2004/05/07 16:36
]	,	element or elements or plurality or portion or separated or		
		dicing or wafer or substrate or dielectric or extending or	İ	
İ		major or face or removing or along or exposing or protecitive		
		or adhesive or juxtaposing or juxtapose or region or unit or		
		individual)		
16	1	("5679977").PN.	USPAT	2004/05/07 16:36
17	1	(("5679977").PN.) and (microelectronic or assembly or	USPAT	2004/05/07 16:36
		element or elements or plurality or portion or separated or		
		dicing or wafer or substrate or dielectric or extending or		
		major or face or removing or along or exposing or protecitive		
j		or adhesive or juxtaposing or juxtapose or region or unit or		
		individual)		
18	460	438/51	USPAT	2004/05/07 16:38
19	274	438/55	USPAT	2004/05/07 16:38
20	438	438/64	USPAT	2004/05/07 16:38
21	1387	438/107	USPAT	2004/05/07 16:39
22	1644	438/108	USPAT	2004/05/07 16:39
23	627	438/110	USPAT	2004/05/07 16:39

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Γ.	24	977	438/113	USPAT	2004/05/07 16:39
	25	1749	438/118	USPAT	2004/05/07 16:39
	26	598	438/119	USPAT	2004/05/07 16:39

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